## **DSG-RICH R&D Meeting**

**Date: August 23, 2021** 

Time: 11:00 AM - 12:00 PM

<u>Attendees</u>: Mary Ann Antonioli, Aaron Brown, Peter Bonneau, Pablo Campero, Brian Eng, George Jacobs, Tyler Lemon, Marc McMullen, and Amrit Yegneswaran

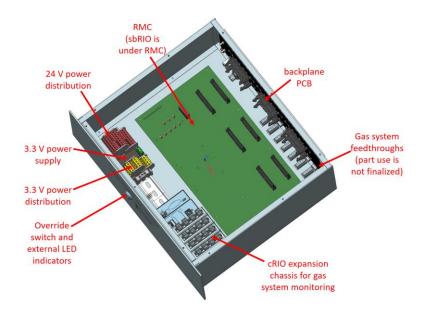
## 1. Discussed exterior I<sup>2</sup>C cabling

- 1. Cable discussed last week has larger overall diameter and individual conductor diameter than most RJ45 connectors can accommodate
  - Waiting for vendor replies on quotes and quantity availability of alternatives
- 2. Since we know cable lengths need to be ~60 feet, the same cable assemblies as the interior I<sup>2</sup>C cables could also be used

## 2. Interlock chassis height increased to 4U (7")

Tyler Lemon

- 1. Height increased to give more room between backplane PCB and feedthroughs (power, network, and gas system signals)
- 2. Chassis components rearranged to take advantage of additional space
  - cRIO expansion chassis moved to same DIN rail as power distribution terminals
  - RMC and backplane PCB centered in chassis



## 3. Backplane PCB routing and placement complete; review underway

Peter Bonneau, Aaron Brown, Pablo Campero, Brian Eng, Tyler Lemon, and Marc McMullen